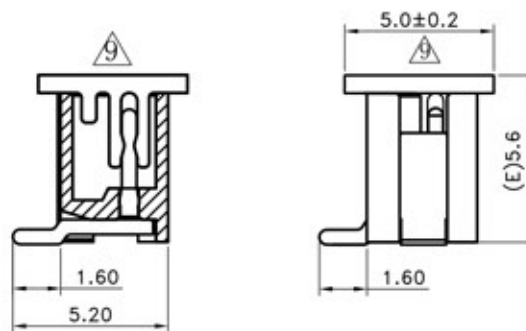
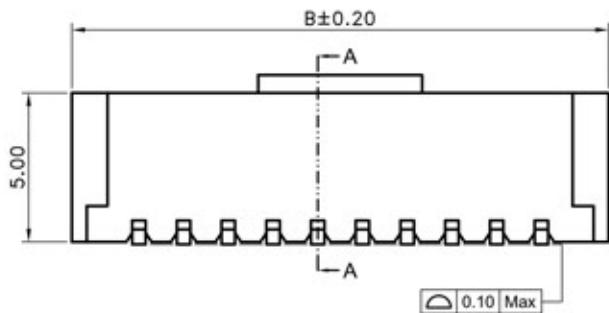


Assembly Layout (REF.)



A-A Section

With Cap

■ SPECIFICATIONS

- Voltage Rating : 50V AC/DC
- Current Rating : 1A AC/DC
- Withstanding Voltage : 500V AC/minute
- Insulation Resistance : 500MΩ min
- Temperature Range : - 25°C to + 85°C
- Contact Resistance : 20mΩ max

■ WAFER

- Part No. : JS-1174V-XX (XX)XX
- Code No. ① ② ③

① Poles No. : 2 ~ 15 (Straight)

② Contact Plated :

- Blank : Tin Plated
- NM : Matte -Tin
- G : Gold Plated

③ Base Color :

- Blank : Natural
- RD : Red
- GR : Green
- BU : Blue

• Material :

1. Contact : Brass, Plated: Refer Above Options
2. Base: Nylon 9T UL94V-0
3. Cap: Nylon PA46 UL94V-0

• Mating Housing : JS-1173-XX

• Mating Terminal : JS-1173-T

• Packing : Tape & Reel

Poles	Dimensions (mm)		
	A	B	C
2	1.50	6.00	3.60
3	3.00	7.50	5.10
4	4.50	9.00	6.60
5	6.00	10.50	8.10
6	7.50	12.00	9.60
7	9.00	13.50	11.10
8	10.50	15.00	12.60
9	12.00	16.50	14.10
10	13.50	18.00	15.60
11	15.00	19.50	17.10
12	16.50	21.00	18.60
13	18.00	22.50	20.10
14	19.50	24.00	21.60
15	21.00	25.50	23.10



喬訊電子工業股份有限公司
CHYAO SHIUNN
ELECTRONIC INDUSTRIAL LTD.

PART NO JS-1174V-XX

1.50mm SMT Series Wire to Board Connector Wafer

APPROVED BY	SCALE	UNIT	TOLERANCE	LTR	REVISION RECORD	NAME	DATE	LTR	REVISION RECORD	NAME	DATE
張育瑞	1:1	mm	.0 ±0.30	▲	ECR RoHS compliant	龔志紅	2005/05/23	▲	合併圖面·增加顏色選項	吳弘文	2012/08/20
CHECKED BY	PROJ	VER NO.	.00 ±0.20	▲	ECR200506-003	龔志紅	2005/06/07	▲	修改蓋子部份的結構	王睿	2015/05/18
周家慶	⊕ ⊖	a9	.000 ±0.10	▲	ECR 200601-008	陳文松	2006/01/06	▲			
DRAWN BY	DATE	SIZE	ANGLE	▲	ECR 200802-014	黃科源	2008/02/26		CUSTOMER		
王睿	2015/05/18	A4	0° ±1°	▲	ECR 200805-011	黃科源	2008/05/27				
			.0° ±	▲	ECR 200903-007	黃科源	2009/03/13				
			SHEET 1/1	▲	ECR 200912-003	林文泰	2009/12/17		Conforms to The RoHS Instruction		